

HAT1065R

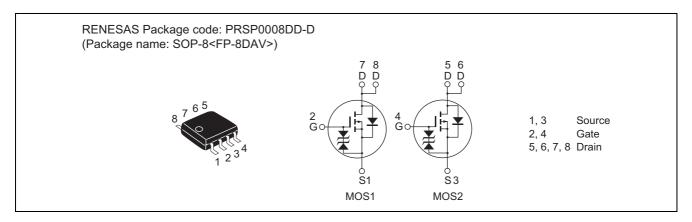
Silicon P Channel Power MOS FET High Speed Power Switching

REJ03G0579-0200 Rev.2.00 Apr 04, 2006

Features

- Low on-resistance
- Capable of –4 V gate drive
- High density mounting

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	-200	V
Gate to source voltage	V _{GSS}	±15	V
Drain current	I _D	-0.25	А
Drain peak current	I _{D(pulse)} Note1	-1	А
Body-drain diode reverse drain current	I _{DR}	-0.25	А
Channel dissipation	Pch Note2	1.3	W
	Pch Note3	2	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. 1 Drive operation ; When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW \leq 10 s

3. 2 Drive operation; When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW \leq 10 s

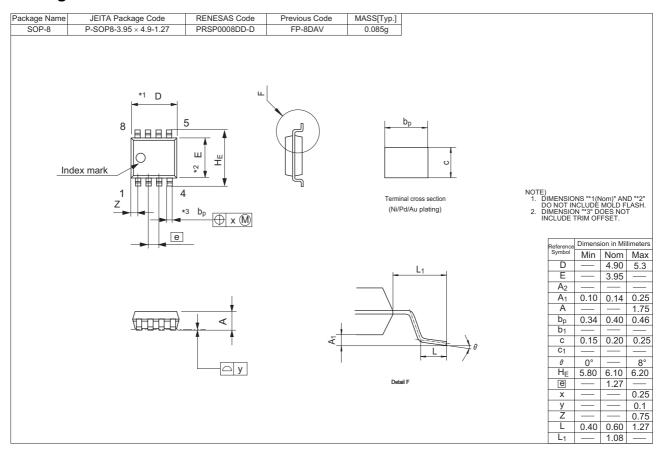
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-200	_	_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±15	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	- 5	μΑ	$V_{DS} = -200 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-1.0	_	-2.0	V	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$
Static drain to source on state	R _{DS(on)}	_	5.0	6.2	Ω	$I_D = -0.25 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note4}}$
resistance	R _{DS(on)}	_	6.0	7.5	Ω	$I_D = -0.25 \text{ A}, V_{GS} = -4 \text{ V}^{\text{Note4}}$
	R _{DS(on)}	_	7.0	10.0	Ω	$I_D = -1 \text{ A}, V_{GS} = -5 \text{ V}^{\text{Note4}}$
Forward transfer admittance	y _{fs}	0.29	0.45	_	S	$I_D = -0.25 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note4}}$
Input capacitance	Ciss	_	140	_	pF	$V_{DS} = -10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	37	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	10	_	pF	
Turn-on delay time	t _{d(on)}	_	12	_	ns	$V_{GS} = -5 \text{ V}, I_D = -0.25 \text{ A}$
Rise time	t _r	_	9	_	ns	$V_{DD} \cong -30 \text{ V}$
Turn-off delay time	t _{d(off)}	_	25	_	ns	
Fall time	t _f	_	15	_	ns	
Body-drain diode forward voltage	V_{DF}	_	-0.9	-1.4	V	$I_F = -0.25 \text{ A}, V_{GS} = 0^{\text{Note4}}$

Notes: 4. Pulse test

Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT1065R-EL-E	2500 pcs	Taping

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